

## **Trench Power MOSFET**

## NTJS3157N

## 20 V, 4.0 A, Single N-Channel, SC-88

#### **Features**

- Leading Trench Technology for Low R<sub>DS(ON)</sub> Extending Battery Life
- Fast Switching for Increased Circuit Efficiency
- SC-88 Small Outline (2 x 2 mm) for Maximum Circuit Board Utilization, Same as SC-70-6
- Pb-Free Packages are Available

#### **Applications**

- DC-DC Conversion
- Low Side Load Switch
- Cell Phones, Computing, Digital Cameras, MP3s and PDAs

#### MAXIMUM RATINGS (T<sub>J</sub> = 25°C unless otherwise stated)

Parameter			Symbol	Value	Unit
Drain-to-Source Voltage			$V_{DSS}$	20	V
Gate-to-Source Voltage			$V_{GS}$	±8.0	V
Continuous Drain Current (Note 1)	Steady State	T <sub>A</sub> = 25 °C	I <sub>D</sub>	3.2	Α
		T <sub>A</sub> = 85 °C		2.3	
	t ≤ 5 s	T <sub>A</sub> = 25 °C		4.0	
Power Dissipation (Note 1)	Steady State	T <sub>A</sub> = 25 °C	P <sub>D</sub>	1.0	W
Pulsed Drain Current $t_p = 10 \mu s$			I <sub>DM</sub>	10	Α
Operating Junction and Storage Temperature			T <sub>J</sub> , T <sub>STG</sub>	–55 to 150	°C
Source Current (Body Diode)			I <sub>S</sub>	1.6	Α
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)			TL	260	°C

#### THERMAL RESISTANCE RATINGS (Note 1)

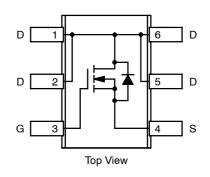
Parameter	Symbol	Max	Unit
Junction-to-Ambient - Steady State	$R_{\theta JA}$	125	°C/W
Junction-to-Ambient - t ≤ 5 s	$R_{\theta JA}$	80	
Junction-to-Lead - Steady State	$R_{ heta JL}$	45	

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

1. Surface mounted on FR4 board using 1 in sq pad size (Cu area = 1.127 in sq [1 oz] including traces).

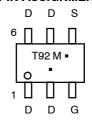
V <sub>(BR)DSS</sub>	R <sub>DS(on)</sub> Typ	I <sub>D</sub> Max		
	45 m $\Omega$ @ 4.5 V			
20 V	55 mΩ @ 2.5 V	4.0 A		
	70 m $\Omega$ @ 1.8 V			

#### SC-88 (SOT-363)



# MARKING DIAGRAM & PIN ASSIGNMENT





T92 = Device Code

M = Date Code

Pb-Free Package

(Note: Microdot may be in either location)



## **NTJS3157N**

#### **ELECTRICAL CHARACTERISTICS** (T<sub>J</sub> = 25°C unless otherwise stated)

Parameter	Symbol	Test Condition		Min	Тур	Max	Unit
OFF CHARACTERISTICS	•				•		•
Drain-to-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		20			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V <sub>(BR)DSS</sub> /T <sub>J</sub>	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 250 μA			12		mV/°C
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 16 V	T <sub>J</sub> = 25°C			1.0	μΑ
			T <sub>J</sub> = 85°C			5.0	
Gate-to-Source Leakage Current	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8.0 \text{ V}$				±100	nA
ON CHARACTERISTICS (Note 2)	•						•
Gate Threshold Voltage	V <sub>GS(TH)</sub>	V <sub>GS</sub> = V <sub>DS</sub> , I <sub>D</sub> = 250 μA		0.40			V
Negative Threshold Temperature Coefficient	V <sub>GS(TH)</sub> /T <sub>J</sub>				-4.0		mV/°C
Drain-to-Source On Resistance	R <sub>DS(on)</sub>	$R_{DS(on)}$ $V_{GS} = 4.5 \text{ V}, I_D = 4.0 \text{ A}$ $V_{GS} = 2.5 \text{ V}, I_D = 3.6 \text{ A}$			45	60	mΩ
					55	70	
		V <sub>GS</sub> = 1.8 V, I <sub>D</sub> = 2.0 A			70	85	
Forward Transconductance	9 <sub>FS</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 3.2 A			9.0		S
CHARGES AND CAPACITANCES	•				•	•	
Input Capacitance	C <sub>ISS</sub>	V <sub>GS</sub> = 0 V, f = 1.0 MHz, V <sub>DS</sub> = 10 V			500		pF
Output Capacitance	C <sub>OSS</sub>				75		
Reverse Transfer Capacitance	C <sub>RSS</sub>				60		
Total Gate Charge	Q <sub>G(TOT)</sub>				6.9	15	nC
Gate-to-Source Charge	$Q_{GS}$	V <sub>GS</sub> = 4.5 V, V <sub>DS</sub> = 10 V, I <sub>D</sub> = 3.2 A			1.0		┦
Gate-to-Drain Charge	$Q_{GD}$				1.8		
SWITCHING CHARACTERISTICS (No	ote 3)				•	•	
Turn-On Delay Time	t <sub>d(on)</sub>				6.0	15	ns
Rise Time	t <sub>r</sub>	Voc = 4.5 V. V	nn = 10 V.		12	25	1
Turn-Off Delay Time	t <sub>d(off)</sub>	$V_{GS} = 4.5 \text{ V}, V_{DD} = 10 \text{ V},$ $I_{D} = 0.5 \text{ A}, R_{G} = 6.0 \Omega$			21	45	┦
Fall Time	t <sub>f</sub>				11	25	
DRAIN-SOURCE DIODE CHARACTE	RISTICS						
Forward Diode Voltage	V <sub>SD</sub>	V <sub>GS</sub> =0 V, I <sub>S</sub> = 1.6 A	T <sub>J</sub> = 25°C		0.7	1.0	V
Reverse Recovery Time	t <sub>RR</sub>		•		15		ns
Charge Time	Ta	$V_{GS} = 0 \text{ V, } dI_{S}/dt = 100 \text{ A/}\mu\text{s,}$ $I_{S} = 1.6 \text{ A}$			12		
Discharge Time	T <sub>b</sub>				3.0		
Reverse Recovery Charge	Q <sub>RR</sub>				5.0		nC

Pulse Test: pulse width ≤ 300 μs, duty cycle ≤ 2%.
 Switching characteristics are independent of operating junction temperatures.